L	Hits	Search Text	T DB	Time stamp
Number				
1	369511	wafer	USPAT;	2004/11/01
			US-PGPUB;	10:16
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
2	1276	(alignment align aligned aligning) same	USPAT;	2004/11/01
		(scribe with line)	US-PGPUB;	10:17
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	621	wafer same ((alignment align aligned	USPAT;	2004/11/01
		aligning) same (scribe with line))	US-PGPUB;	10:17
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
4	188	(through via hole) same (wafer same	USPAT;	2004/11/01
		((alignment align aligned aligning) same	US-PGPUB;	10:20
		(scribe with line)))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	l i
5	123	(mark point cross position) same	USPAT;	2004/11/01
	1	((through via hole) same (wafer same	US-PGPUB;	11:00
	,	((alignment align aligned aligning) same	EPO; JPO;	
		(scribe with line))))	DERWENT;	
			IBM_TDB	
6	12765	wafer with (thru through hole via) with	USPAT;	2004/11/01
		(intersection mark point cross position)	US-PGPUB;	11:01
			EPO; JPO;	1
			DERWENT;	
_			IBM_TDB	
7	35	(wafer with (thru through hole via) with	USPAT;	2004/11/01
		(intersection mark point cross position)	US-PGPUB;	11:01
	,) same ((alignment align aligned	EPO; JPO;	
		aligning) same (scribe with line))	DERWENT;	
			IBM_TDB_	l